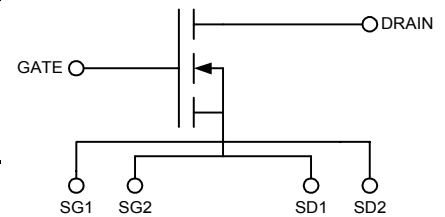


N-Channel Enhancement Mode
 Low Q_g and R_g
 High dv/dt
 Nanosecond Switching

$V_{DSS} = 500 V$
 $I_{D25} = 4.5 A$
 $R_{DS(on)} = 1.5 \Omega$
 $P_{DC} = 200W$

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ C$ to $150^\circ C$	500	V
V_{DGR}	$T_J = 25^\circ C$ to $150^\circ C$; $R_{GS} = 1 M\Omega$	500	V
V_{GS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_c = 25^\circ C$	4.5	A
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	27	A
I_{AR}	$T_c = 25^\circ C$	4.5	A
E_{AR}	$T_c = 25^\circ C$	-	mJ
dv/dt	$I_S \leq I_{DM}$, $di/dt \leq 100 A/\mu s$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$, $R_G = 0.2 \Omega$	3.5	V/ns
	$I_S = 0$	>200	V/ns
P_{DC}		200	W
P_{DHS}	$T_c = 25^\circ C$ Derate 4.4W/ $^\circ C$ above $25^\circ C$	80	W
P_{DAMB}	$T_c = 25^\circ C$	3.5	W
R_{thJC}		0.74	C/W
R_{thJHS}		1.50	C/W



Symbol	Test Conditions	Characteristic Values		
		$T_J = 25^\circ C$ unless otherwise specified		
		min.	typ.	max.
V_{DSS}	$V_{GS} = 0 V$, $I_D = 3 ma$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4 ma$	2	3	4 V
I_{GSS}	$V_{GS} = \pm 20 V_{DC}$, $V_{DS} = 0$			± 100 nA
I_{DSS}	$V_{DS} = 0.8 V_{DSS}$, $T_J = 25^\circ C$ $V_{GS} = 0$, $T_J = 125^\circ C$			25 μA
				250 μA
$R_{DS(on)}$	$V_{GS} = 15 V$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2\%$			1.5 Ω
g_{fs}	$V_{DS} = 15 V$, $I_D = 0.5 I_{D25}$, pulse test	2.7	4.0	S
T_J		-55		+175 $^\circ C$
T_{JM}			175	$^\circ C$
T_{stg}		-55		+175 $^\circ C$
T_L	1.6mm (0.063 in) from case for 10 s		300	$^\circ C$
Weight			2	g

Features

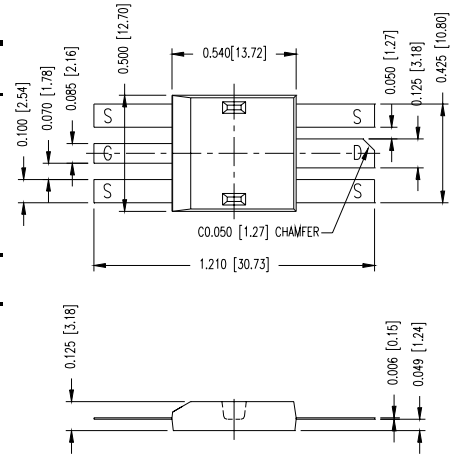
- Isolated Substrate
 - high isolation voltage (>2500V)
 - excellent thermal transfer
 - Increased temperature and power cycling capability
- IXYS advanced low Q_g process
- Low gate charge and capacitances
 - easier to drive
 - faster switching
- Low $R_{DS(on)}$
- Very low insertion inductance (<2nH)
- No beryllium oxide (BeO) or other hazardous materials

Advantages

- Optimized for RF and high speed switching at frequencies to >100MHz
- Easy to mount—no insulators needed
- High power density

Symbol Test Conditions Characteristic Values
($T_J = 25^\circ\text{C}$ unless otherwise specified)

		min.	typ.	max.
R_G				5 Ω
C_{iss}			700	pF
C_{oss}	$V_{GS} = 0\text{ V}, V_{DS} = 0.8 V_{DSS(max)}, f = 1\text{ MHz}$		90	pF
C_{rss}			5	pF
C_{stray}	Back Metal to any Pin		16	pF
T_{d(on)}			4	ns
T_{on}	$V_{GS} = 15\text{ V}, V_{DS} = 0.8 V_{DSS}, I_D = 0.5 I_{DM}$		4	ns
T_{d(off)}	$R_G = 0.2\ \Omega$ (External)		4	ns
T_{off}			4	ns
Q_{g(on)}		16		40 nC
Q_{gs}	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$	2.0		6.0 nC
Q_{gd}		8.0		20 nC



Source-Drain Diode Characteristic Values
($T_J = 25^\circ\text{C}$ unless otherwise specified)

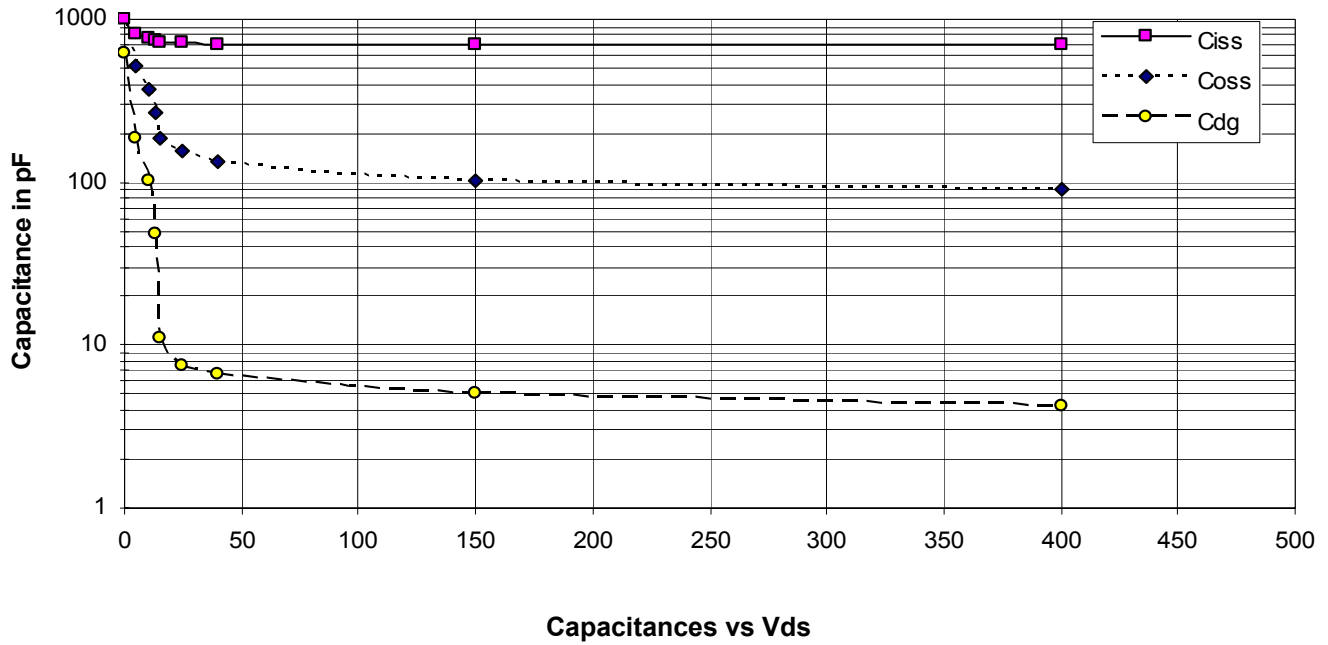
Symbol	Test Conditions	min.	typ.	max.
I_S	$V_{GS} = 0\text{ V}$			4.5 A
I_{SM}	Repetitive; pulse width limited by T_{JM}			27 A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V},$ Pulse test, $t \leq 300\ \mu\text{s},$ duty cycle $\leq 2\%$			1.4 V
T_{rr}			900	ns

For detailed device mounting and installation instructions, see the “DE-Series MOSFET Mounting Instructions” technical note on IXYS RF’s web site at www.ixysrf.com/Technical_Support/App_notes.html

IXYS RF reserves the right to change limits, test conditions and dimensions.

IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

- | | | | | | |
|-----------|-----------|-----------|-----------|-----------|-----------|
| 4,835,592 | 4,850,072 | 4,881,106 | 4,891,686 | 4,931,844 | 5,017,508 |
| 5,034,796 | 5,049,961 | 5,063,307 | 5,187,117 | 5,237,481 | 5,486,715 |
| 5,381,025 | 5,640,045 | | | | |



501N04A DE-SERIES SPICE Model

The DE-SERIES SPICE Model is illustrated in Figure 1. The model is an expansion of the SPICE level 3 MOSFET model. It includes the stray inductive terms L_G , L_S and L_D . R_d is the $R_{DS(ON)}$ of the device, R_{ds} is the resistive leakage term. The output capacitance, C_{OSS} , and reverse transfer capacitance, C_{RSS} are modeled with reversed biased diodes. This provides a varactor type response necessary for a high power device model. The turn on delay and the turn off delay are adjusted via R_{on} and R_{off} .

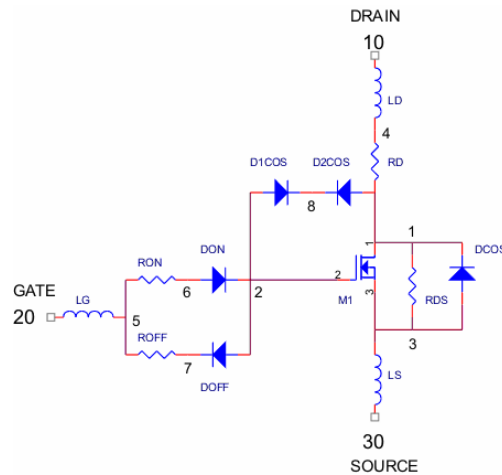


Figure 1 DE-SERIES SPICE Model

This SPICE model may be downloaded as a text file from the DEI web site at www.directedenergy.com/spice.htm

Net List:

```
*SYM=POWMOSN
.SUBCKT 501N04A 10 20 30
* TERMINALS: D G S
* 500 Volt 4.5 Amp 1.5 Ohm N-Channel Power MOSFET 10-30-2001
M1 1 2 3 3 DMOS L=1U W=1U
RON 5 6 9.5
DON 6 2 D1
ROF 5 7 3.5
DOF 2 7 D1
D1CRS 2 8 D2
D2CRS 1 8 D2
CGS 2 3 .6N
RD 4 1 1.5
DCOS 3 1 D3
RDS 1 3 5.0MEG
LS 3 30 .1N
LD 10 4 1N
LG 20 5 1N
.MODEL DMOS NMOS (LEVEL=3 VTO=3.0 KP=6.0)
.MODEL D1 D (IS=.5F CJO=1P BV=100 M=.5 VJ=.6 TT=1N)
.MODEL D2 D (IS=.5F CJO=175P BV=500 M=.5 VJ=.6 TT=1N RS=10M)
.MODEL D3 D (IS=.5F CJO=250P BV=500 M=.3 VJ=.4 TT=400N RS=10M)
.ENDS
```

Doc #9200-0240 Rev 3
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